

Advanced Product Change Notification Withdrawal

202009025AW : Withdrawal: APCN NX20P5090UK FAB EXPANSION SSMC TO TSMC F10

Note: This notice is NXP Company Proprietary.

Issue Date: Mar 28, 2021

Here is your personalized notification about a NXP general announcement. For detailed information we invite you to view this notification online

Management summary

To meet increasing customer demand, expand NX20P5090UK fab from SSMC to TSMC F10. - update, the project has been subsequently cancelled.

Change Category

[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
	Process []Assembly Materials []Assembly	Process []Product Marking []Assembly Materials []Mechanical Specification	Process []Product Marking Process []Assembly []Mechanical Specification []Test Equipment []Assembly []Packing/Shipping/Labeling []Test

[]Firmware []Other

PCN Overview Description

Description

NXP Semiconductor is annoucing the introduction of Taiwan Semiconductor Manufacturing Compony Fab10 (TSMC F10), Shanghai, China as a dual source wafer manufacturing location for the NX20P5090UK.

Reason for change:

The fab manufacturing site capacity expansion to TSMC F10 will improve NXP's ability to meet increasing customer demand and still maintain supply from the original fab (SSMC).

Identification of affected products:

Line C marking XtDYYWW, X = foundry location, "Z" is for SSMC and "N" is for TSMC F10.

Reason

The fab manufacturing site capacity expansion to TSMC F10 will improve NXP's ability to meet increasing customer demand and still maintain supply from the original fab (SSMC).

Identification of Affected Products Top Side Marking Product Availability

Sample Information

Samples are available upon request **Production** Planned first shipment Dec 24, 2020 **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

No Impact on form, fit, function, reliability or quality **Data Sheet Revision** A new datasheet will be issued

Timing and Logistics

The Self Qualification Report will be ready on Sep 18, 2020. The Final PCN is planned to be issued on: Jan 21, 2021. In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Apr 27, 2021.

Remarks

Withdraw the APCN 202009025A, the fab tranfer of NX20P5090 wa cancelled.

Withdrawal Information

NXP decided to stop the NX20P5090 fab expansion because the current SSMC has enough capacity to support customer demands.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization. This message has been automatically distributed. Please do not reply.

NXP Semiconductors High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2021 NXP Semiconductors. All rights reserved.

Affected OPN

NX20P5090UKAZ